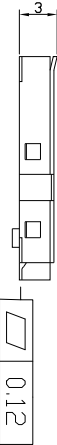
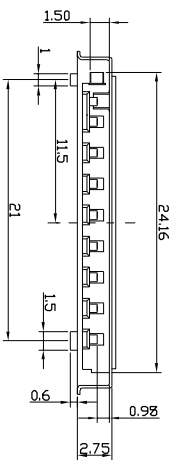


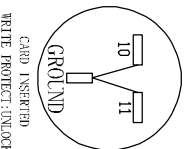
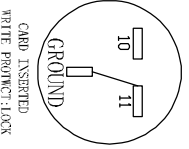
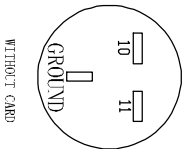
P.C.B Layout

SD CARD PIN DESIGN

Pin NO.	Name	Description
1#	CD/DAT3	Card detect/data I/O
2#	CMD	Command
3#	VSS1	Ground
4#	VDD	Power
5#	CLK	Clock
6#	VSS2	Ground
7#	DAT0	Data I/O
8#	DAT1	Data I/O
9#	DAT2	Data I/O



- 10—WRITE PROTECT PIN
- 11—CARD DETECT PIN
- GROUND(SHELL)—COMMON PIN



NOTES:

1. MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
CONTACT: COPPER ALLOY
SHELL: COPPER ALLOY
2. PLATING
CONTACT AREA: GOLD PLATED OVER Ni
SOLDER TAIL: 100μ MIN Sn PLATED OVER Ni
SPEC SEE ORDERING INFORMATION
3. RATING
SHELL, SOLDER AREA: GOLD PLATED OVER Ni
CURRENT RATING: 0.5A
VOLTAGE RATING: 250V RMS
OPERATING TEMPERATURE: -25°C ~ 90°C
4. SPECIFICATION
CONTACT RESISTANCE: 40 MΩ @ 110 OHMS
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC MegOHMS
INSULATION RESISTANCE: 100 MegOHMS
INSERTION FORCE: 40N MAX
SEPARATION FORCE: 2N MIN

版本REV	变更履历REVISION NOTE	日期DATE	备注公差 TOLERANCE	100% BRANCE
			X ±0.15	X° ±1°
			X.X ±0.10	X.X° ±0.5°
			X.XX ±0.05	X.XX° ±0.05°
			X.XXX ±0.005	X.XXX ±0.005°
			X.XXX ±0.003	X.XXX ±0.003°
			X.XXX ±0.002	X.XXX ±0.002°
			X.XXX ±0.001	X.XXX ±0.001°

深圳市骏东电子有限公司
SD短卡座

图号MODEL: 单位名称: mm 页码SHEET: 共1页 第1页

设计DES' D	付泽
审核CHK' D	林春
批准APPV' D	张志敏



A4